HVC KYOTO 2018

**Pitch Application Form (Deadline: 2018/4/9）**

Please Submit this document file to hvckyoto@krp.co.jp

**Conference Date: Tuesday, 2018/7/3**

**Venue: Kyoto Research Park (93 Chudoji-Awatacho, Shimogyo-ku, Kyoto)**

**◆Basic Information**

We will disclose the information with ※ in our website & flyer for introduction purposes.

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| **Preferred Pitch Session****(please choose)** | 1. Entrepreneur pitch

(company not formed yet) | 1. Startup Pitch
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| **※Pitch Title** |  |
| **※Name of Speaker** |  |
| **※Speaker Affiliation** **Position at Organization** |  |
| **※Speaker Profile****（30-50 words）** |  |

**◆Content of your Pitch**

[note]Presentation files/posters must be made in English

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| **Your purpose for application:** Please fill in your purpose for pitching at HVC KYOTO 2018 (for Fundraising, searching for potential partners and/or clients, recruitment of executive team members, etc.)  |
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| **Executive Summary of your Business & Technology**Please summarize in 1-2pages. You can use following questions to guide your way in writing your summary. (You can attach additional documents of your plan upon application)* Who is your client? What do you provide to them? What kind of social impact do you want to provide to them?
* What is your technology? What is your superiority among competitors and how far is it in development?
* Where is your market, and how large is it? Who is your forerunner in the market?
* Who is in your team? What are their background and what strengths do they have in bringing your idea/technology to life?
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| **Meeting requests to HVC KYOTO 2018 Partners**At HVC KYOTO 2018, we will have time for setting up individual meetings between you and the partners. If you wish to request a meeting, please fill in the company name which you would like to meet and agenda which you wish to discuss about.（Partner list will be updated at HVC KYOTO website <https://www.krp.co.jp/hvckyoto/>）**Please note that the meeting arrangements are on best effort basis and we may not be able to arrange all of your requests.**  |
| Company name | Meeting agenda |
| Ex) ABC Co. Ltd. | Ex) Discussion about applying our technology to XX disease. Milestones needed to be met for going in to partnership discussions. |
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◆Contact Information

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| --- | --- |
| Name of Contact person |  |
| Position of Contact person |  |
| E-mail address |  |
| Phone number |  |
| Post address in Japan for sending documents | 〒 |

◆for inquries and submission

Makoto Shida, HVC KYOTO 2018 correspondent Application

Kyoto Research Park Corp.

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**◆Organizers of HVC KYOTO 2018 (scheduled)**

Japan External Trade Organization (JETRO), Kyoto Prefecture, Kyoto City, Kyoto Research Park Corp.

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| **Terms and Conditions for application** |
| **※Please note that by submitting your application documents, you will agree to the terms and conditions listed below.**1. Treatment and confidentiality of the application

The documents and files which you have submitted to the HVC KYOTO 2018 secretariat may be shared among the organizers, mentors, and supporters and other parties concerned in organizing HVC KYOTO2018. We will not disclose to third parties without your prior consent by emails or documents. 1. Disclaimer

In submitting this proposal, please make sure to take necessary actions in advance to protect your intellectual property (ie. patent right, utility model right, design right, trademark right, copyright, etc.) and information that can receive legal protection such as trade secret and know-how etc. Please submit materials that can be shared or publicized between the stakeholders. The organizers will not bear any responsibility for these legal rights and legal protection measures etc.1. Participation to the July 3rd and prior mentoring sessions

By submitting this proposal, we regard as having acknowledged in attending the prior mentoring session as well as participating in the event program on July 3rd. If you are unable to visit the venue regarding prior mentoring sessions, you may participate through web conferencing system etc. which we have authorized.1. Participation cost

Submission to this proposal is free. However, please be aware of travel expenses to the venue that occur on the day of prior mentoring and on the day of the event(July 3rd). |